

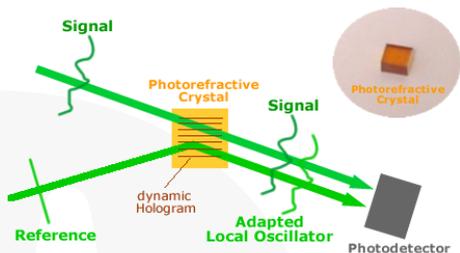
# ULTRA HIGH FREQUENCY LASER RECEIVER



Laser  
Ultrasonics

## TECHNOLOGY

The **Ultra high Frequency** receiver is based on photorefractive two-wave mixing. A dynamic hologram resulting from the interferences between the reference beam and the signal beam is recorded in the photorefractive crystal. The diffraction of the reference beam by the dynamic hologram creates a local oscillator adapted to the signal i.e. same wavefront and same direction. Two-wave mixing in a photorefractive material is equivalent to an adaptive beam splitter. The two beams – signal and adapted local oscillator – are in perfect quadrature and are incident on the photodetector that delivers a homodyne signal.



High performances photorefractive crystals are used with reliable properties to insure an optimum two-wave mixing process. A high voltage field is applied on the photorefractive crystal in order to optimize the coupling and maintain the quadrature between the signal and the diffracted reference (adapted local oscillator). Photorefractive two-wave mixing has been extensively studied over the past 40 years and is a well-controlled process

## FEATURES

- > No high frequency limit
- > Large étendue interferometer
- > High sensitivity on all surface types and materials
- > Continuous detection laser

## EXAMPLES OF APPLICATIONS

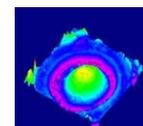
### Material characterization

Laser-ultrasonics are used to measure fundamental material properties such as the elastic modulus, shear modulus and Poisson ratio. Those parameters are of great importance for estimation of active stresses and life service

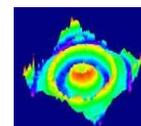
#### Transducer characterization



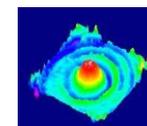
1 MHz piezo, 1 inch  $\Phi$   
1  $\mu$ s pulse excitation



Sample surface at  $t_0$



At  $t_0+1 \mu$ s



At  $t_0+2 \mu$ s

### Acoustic emission

The laser receiver can also be used alone, without the generation laser, to listen to acoustic emission occurring when the sample is under stress. Remote detection of acoustic emission can be used for monitoring during manufacturing processes.

## SPECIFICATIONS

Technology  
Two-Wave mixing

Detection  
Out-Of-Plane

Configuration  
Free-Space

Internal Laser power  
Up to 1.5W @532nm

NESD (out-of-plane motion)  
 $2.10^{-7}$  nm. (W/Hz)<sup>1/2</sup>

Detection bandwidth  
Up to 1Ghz

Dimensions  
492 x 302 x 114 mm<sup>3</sup>

Weight  
16kg

Electrical requirements  
110V / 220V  
50Hz / 60Hz